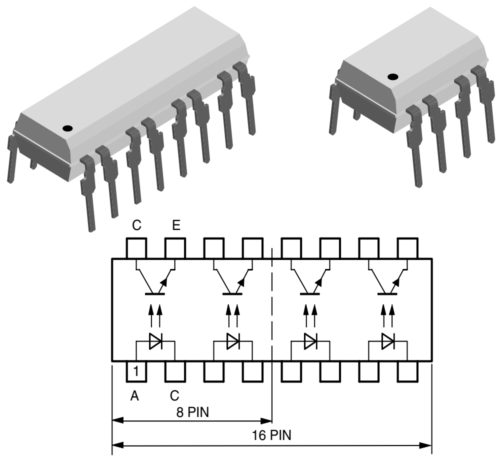
Optocoupler, Phototransistor Output (Dual, Quad Channel)

Features

- Extra low coupling capacity - typical 0.2 pF
- High Common Mode Rejection
- Low temperature coefficient of CTR
- Rated impulse voltage (transient overvoltage) V_{IOTM} = 8 kV peak
- Lead-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



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Agency Approvals

- UL1577, File No. E76222 System Code U, Double Protection
- CSA 22.2 bulletin 5A, Double Protection
- BSI IEC60950 IEC60065
- DIN EN 60747-5-2 (VDE0884)
  DIN EN 60747-5-5 pending
- FIMKO

Applications

Switch-mode power supplies

Line receiver

Computer peripheral interface

Microprocessor system interface

Reinforced Isolation provides circuit protection against electrical shock (Safety Class II)

Circuits for safe protective separation against electrical shock according to safety class II (reinforced isolation):

• For appl. class I - IV at mains voltage ≤ 300 V

• For appl. class I - III at mains voltage ≤ 600 V according to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending, table 2.

Description

The TCET2100/ TCET4100 consists of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode, available in 8 pin (dual channel) and 16 pin (quad channel) package.

The elements are mounted on one leadframe providing a fixed distance between input and output for highest safety requirements.

Creepage current resistance according to VDE 0303/ IEC 60112 **C**omparative **T**racking **I**ndex:
CTI ≥ 175

Thickness through insulation ≥ 0.75 mm

Order Information

Part	Remarks
TCET2100	CTR 50 - 600 %, Dual Channel, DIP-8
TCET4100	CTR 50 - 600 %, Quad Channel, DIP-16

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified
Stresses in excess of the absolute Maximum Ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute Maximum Rating for extended periods of the time can adversely affect reliability.

Input

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		V_R	6	V
Forward current		I_F	60	mA
Forward surge current	$t_p \leq 10\ \mu s$	I_{FSM}	1.5	A
Power dissipation		P_{diss}	100	mW
Junction temperature		T_j	125	°C

Output

Parameter	Test condition	Symbol	Value	Unit
Collector emitter voltage		V_{CEO}	70	V
Emitter collector voltage		V_{ECO}	7	V
Collector current		I_C	50	mA
Collector peak current	$t_p/T = 0.5$, $t_p \leq 10$ ms	I_{CM}	100	mA
Power dissipation		P_{diss}	150	mW
Junction temperature		T_j	125	°C

Coupler

Parameter	Test condition	Symbol	Value	Unit
Isolation test voltage (RMS)	t = 1 min	V_{ISO}	5000	V_{RMS}
Total power dissipation		P_{tot}	250	mW
Operating ambient temperature range		T_{amb}	- 40 to + 100	°C
Storage temperature range		T_{stg}	- 55 to + 125	°C
Soldering temperature	2 mm from case $t \leq 10$ s	T_{sld}	260	°C

Electrical Characteristics

T_{amb} = 25 °C, unless otherwise specified
Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

Input

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = \pm 50$ mA	V_F		1.25	1.6	V
Junction capacitance	$V_R = 0$ V, f = 1 MHz	C_j		50		pF

Output

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector emitter voltage	$I_C = 1$ mA	V_{CEO}	70			V
Emitter collector voltage	$I_E = 100\ \mu A$	V_{ECO}	7			V
Collector-emitter cut-off current	$V_{CE} = 20$ V, $I_f = 0$, E = 0	I_{CEO}		10	100	nA

Coupler

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector emitter saturation voltage	I_F = 10 mA, I_C = 1 mA	V_{CEsat}			0.3	V
Cut-off frequency	V_{CE} = 5 V, I_F = 10 mA, R_L = 100 Ω	f_c		110		kHz
Coupling capacitance	f = 1 MHz	C_k		0.3		pF

Current Transfer Ratio

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
I_C/I_F	V_{CE} = 5 V, I_F = 5 mA	CTR	50		600	%

Maximum Safety Ratings

(according to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending) see figure 1
This optocoupler is suitable for safe electrical isolation only within the safety ratings.
Compliance with the safety ratings shall be ensured by means of suitable protective circuits.

Input

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward current		I_F			130	mA

Output

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Power dissipation		P_{diss}			265	mW

Coupler

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Rated impulse voltage		V_{IOTM}			8	kV
Safety temperature		T_{si}			150	°C

Insulation Rated Parameters

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Partial discharge test voltage - Routine test	100 %, t_{test} = 1 s	V_{pd}	1.6			kV
Partial discharge test voltage - Lot test (sample test)	t_{Tr} = 60 s, t_{test} = 10 s, (see figure 2)	V_{IOTM}	8			kV
		V_{pd}	1.3			kV
Insulation resistance	V_{IO} = 500 V	R_{IO}	10^{12}			Ω
	V_{IO} = 500 V, T_{amb} = 100 °C	R_{IO}	10^{11}			Ω
	V_{IO} = 500 V, T_{amb} = 150 °C (construction test only)	R_{IO}	10^{9}			Ω

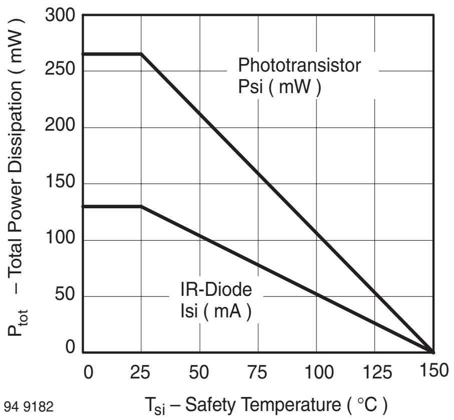


Figure 1. Derating diagram

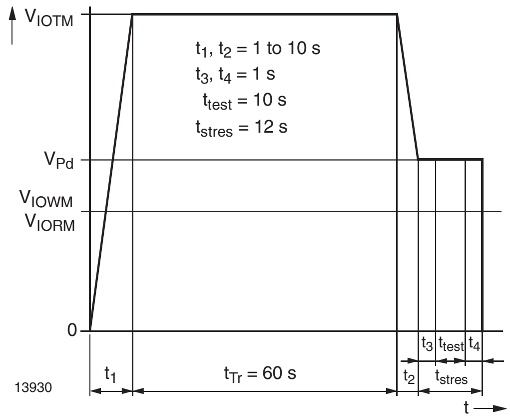


Figure 2. Test pulse diagram for sample test according to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-; IEC60747

Switching Characteristics

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Delay time	V_S = 5 V, I_C = 2 mA, R_L = 100 Ω (see figure 3)	t_d		3.0		µs
Rise time	V_S = 5 V, I_C = 2 mA, R_L = 100 Ω (see figure 3)	t_r		3.0		µs
Turn-on time	V_S = 5 V, I_C = 2 mA, R_L = 100 Ω (see figure 3)	t_{on}		6.0		µs
Storage time	V_S = 5 V, I_C = 2 mA, R_L = 100 Ω (see figure 3)	t_s		0.3		µs
Fall time	V_S = 5 V, I_C = 2 mA, R_L = 100 Ω (see figure 3)	t_f		4.7		µs
Turn-off time	V_S = 5 V, I_C = 2 mA, R_L = 100 Ω (see figure 3)	t_{off}		5.0		µs
Turn-on time	V_S = 5 V, I_F = 10 mA, R_L = 1 kΩ (see figure 4)	t_{on}		9.0		µs
Turn-off time	V_S = 5 V, I_F = 10 mA, R_L = 1 kΩ (see figure 4)	t_{off}		10.0		µs

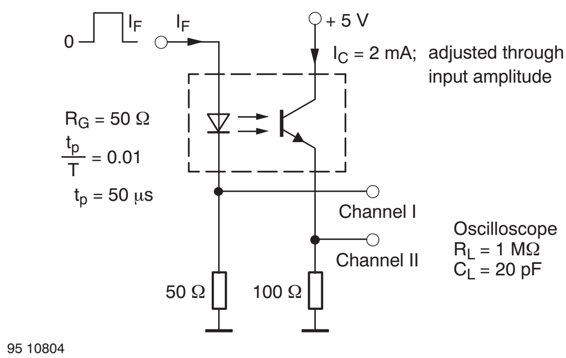


Figure 3. Test circuit, non-saturated operation

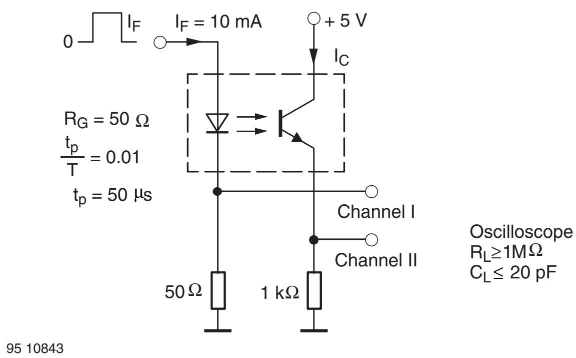
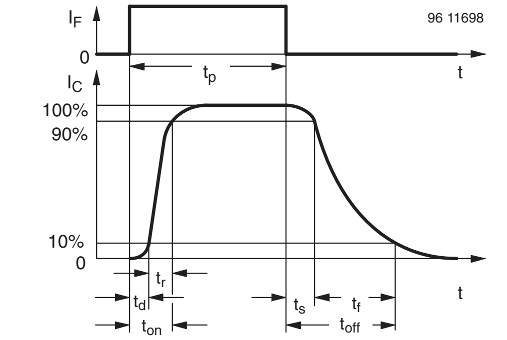


Figure 4. Test circuit, saturated operation



t_p	pulse duration	t_s	storage time
t_d	delay time	t_f	fall time
t_r	rise time	t_{off} (= t_s + t_f)	turn-off time
t_{on} (= t_d + t_r)	turn-on time		

Figure 5. Switching Times

Typical Characteristics (Tamb = 25 °C unless otherwise specified)

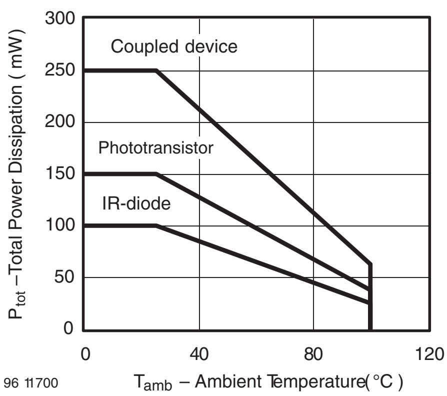


Figure 6. Total Power Dissipation vs. Ambient Temperature

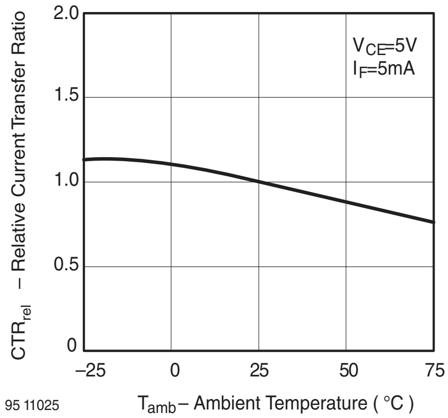


Figure 8. Relative Current Transfer Ratio vs. Ambient Temperature

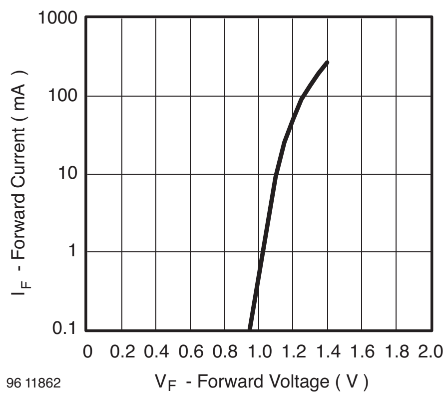


Figure 7. Forward Current vs. Forward Voltage

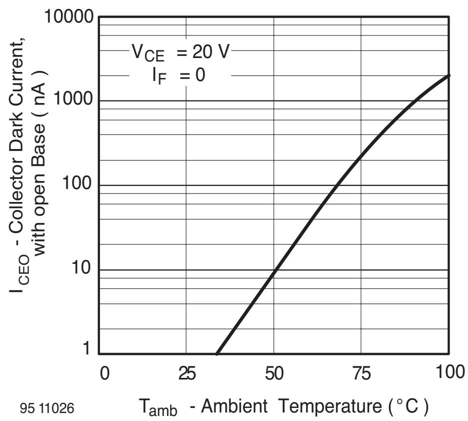


Figure 9. Collector Dark Current vs. Ambient Temperature

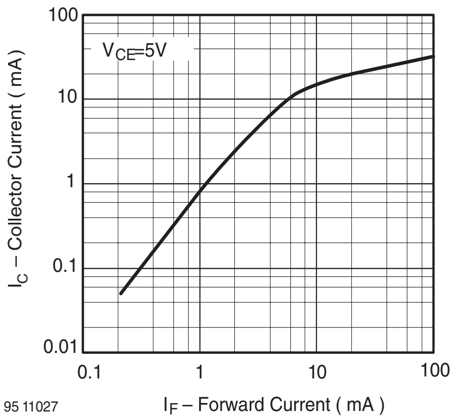


Figure 10. Collector Current vs. Forward Current

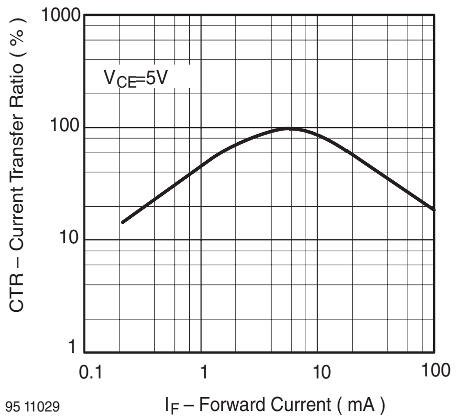


Figure 13. Current Transfer Ratio vs. Forward Current

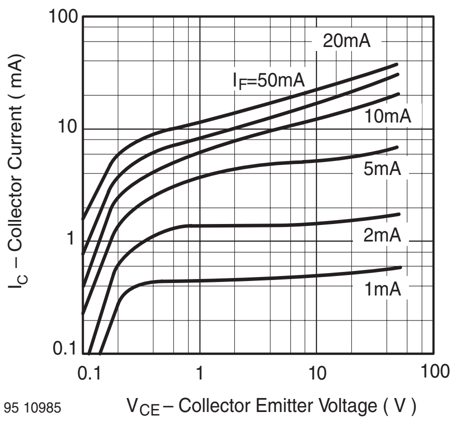


Figure 11. Collector Current vs. Collector Emitter Voltage

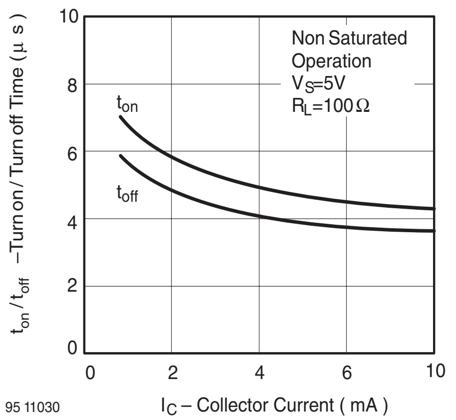


Figure 14. Turn on / off Time vs. Collector Current

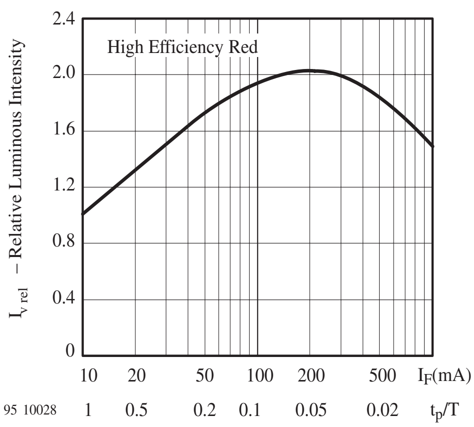


Figure 12. Collector Emitter Saturation Voltage vs. Collector Current

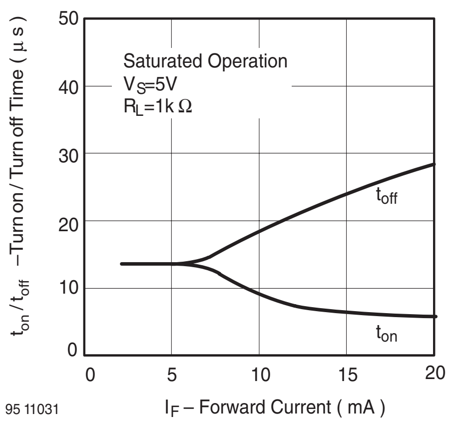
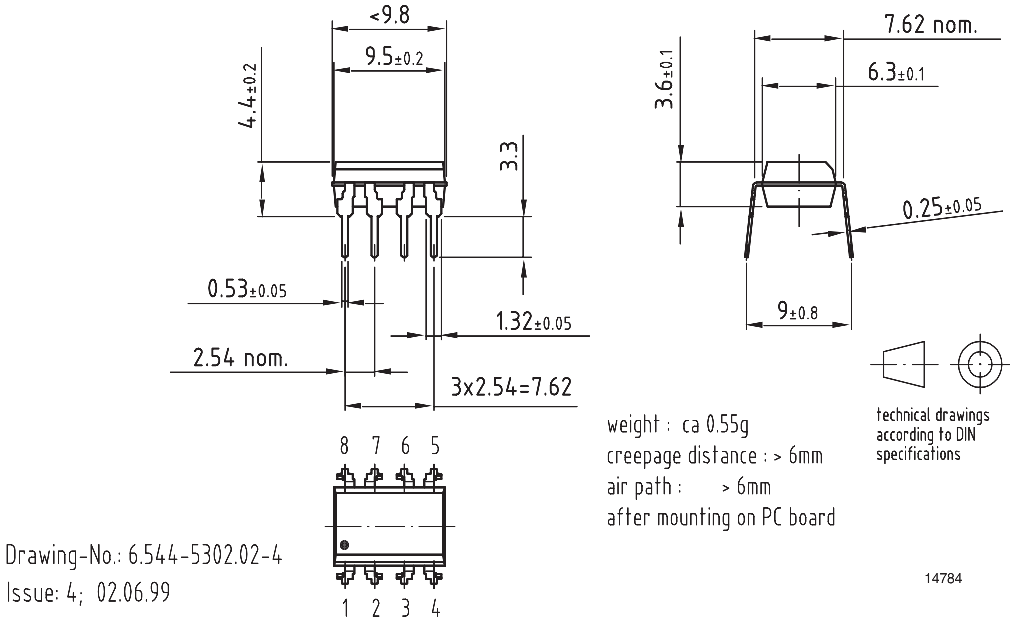
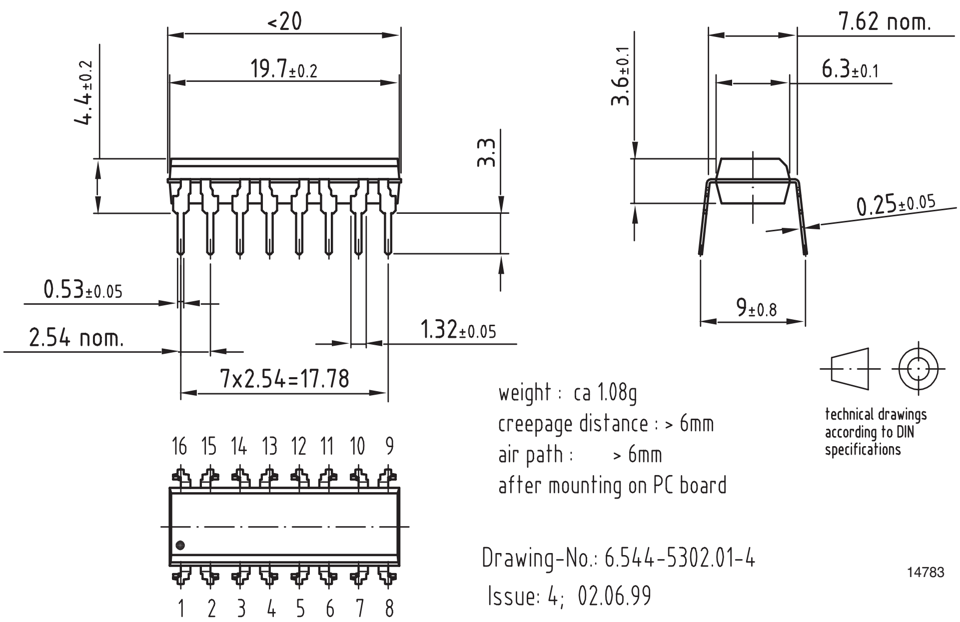


Figure 15. Turn on / off Time vs. Forward Current

Package Dimensions in mm



Package Dimensions in mm



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

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